

# SOT711-1

plastic ball grid array package; 240 balls; body 23 x 23 x 1.75 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA240
<b>Package type industry code</b>	BGA240
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>JEITA package outline code</b>	IC-7315-001
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-11-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A <sub>2</sub>	package height	1.6	-	1.75	1.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	240	-	



2. Package outline

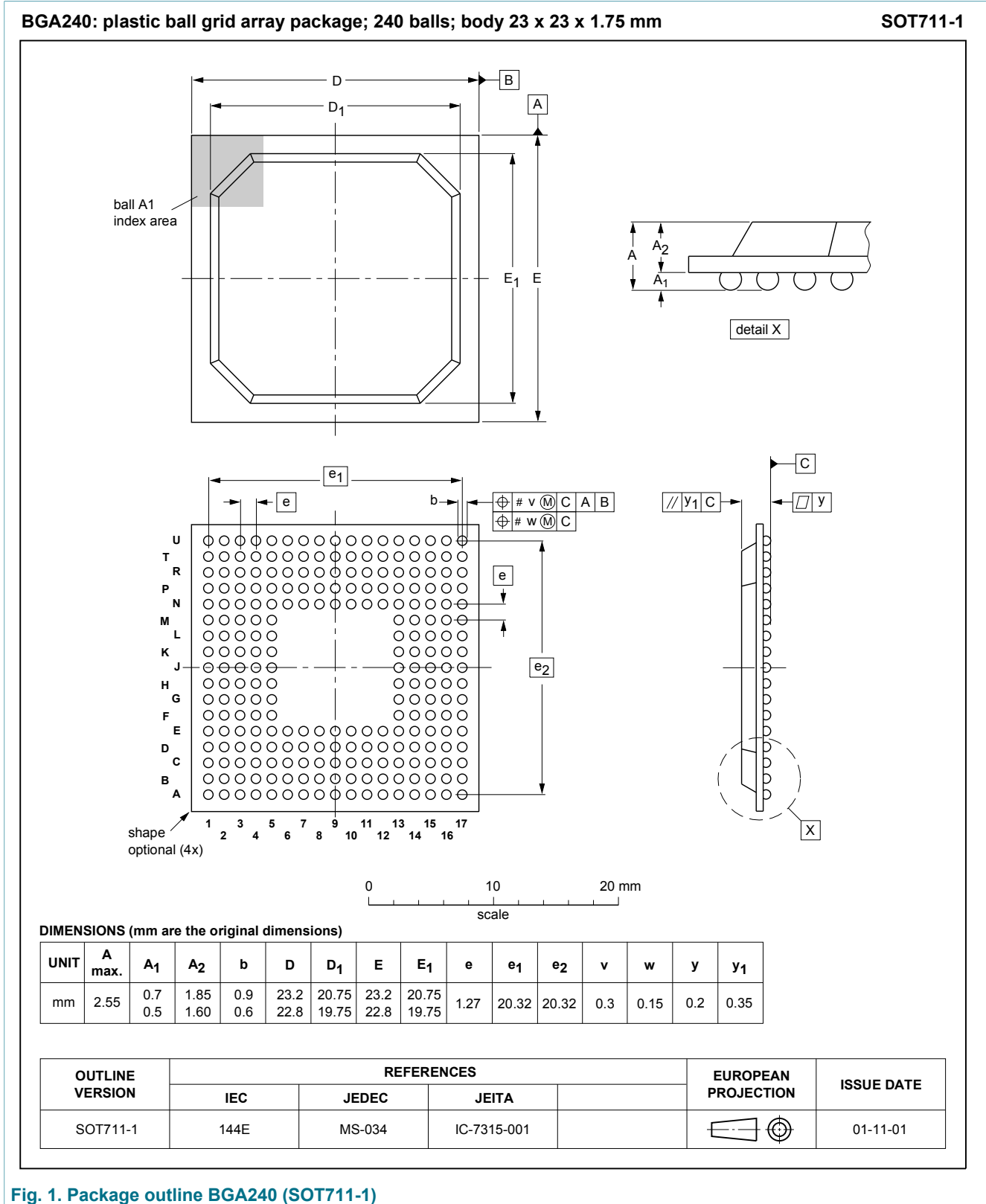
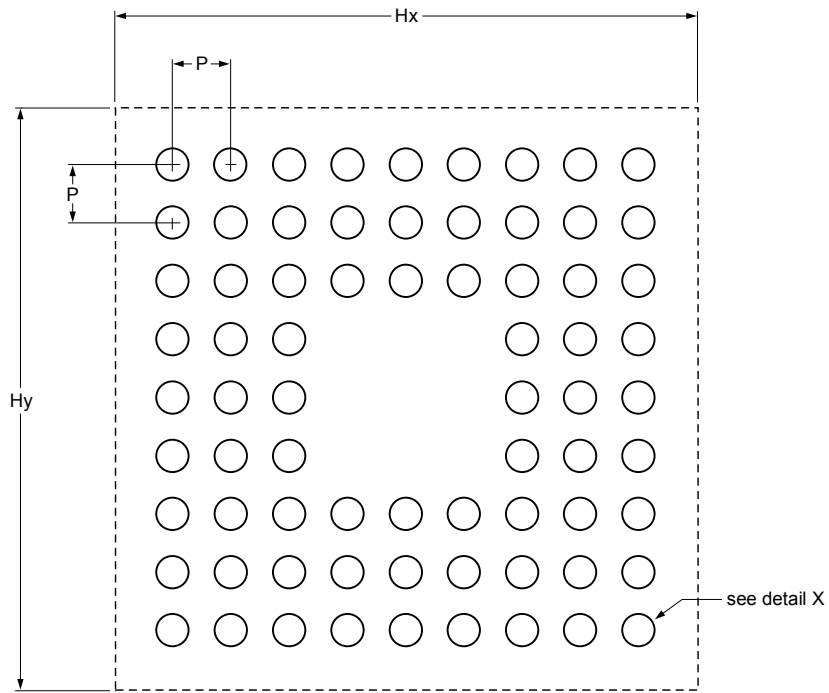


Fig. 1. Package outline BGA240 (SOT711-1)




### 3. Soldering

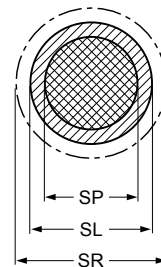
Footprint information for reflow soldering of BGA240 package

SOT711-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

Dimensions in mm

P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	23.575	23.575

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Fig. 2. Reflow soldering footprint for BGA240 (SOT711-1)

## 4. Legal information

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